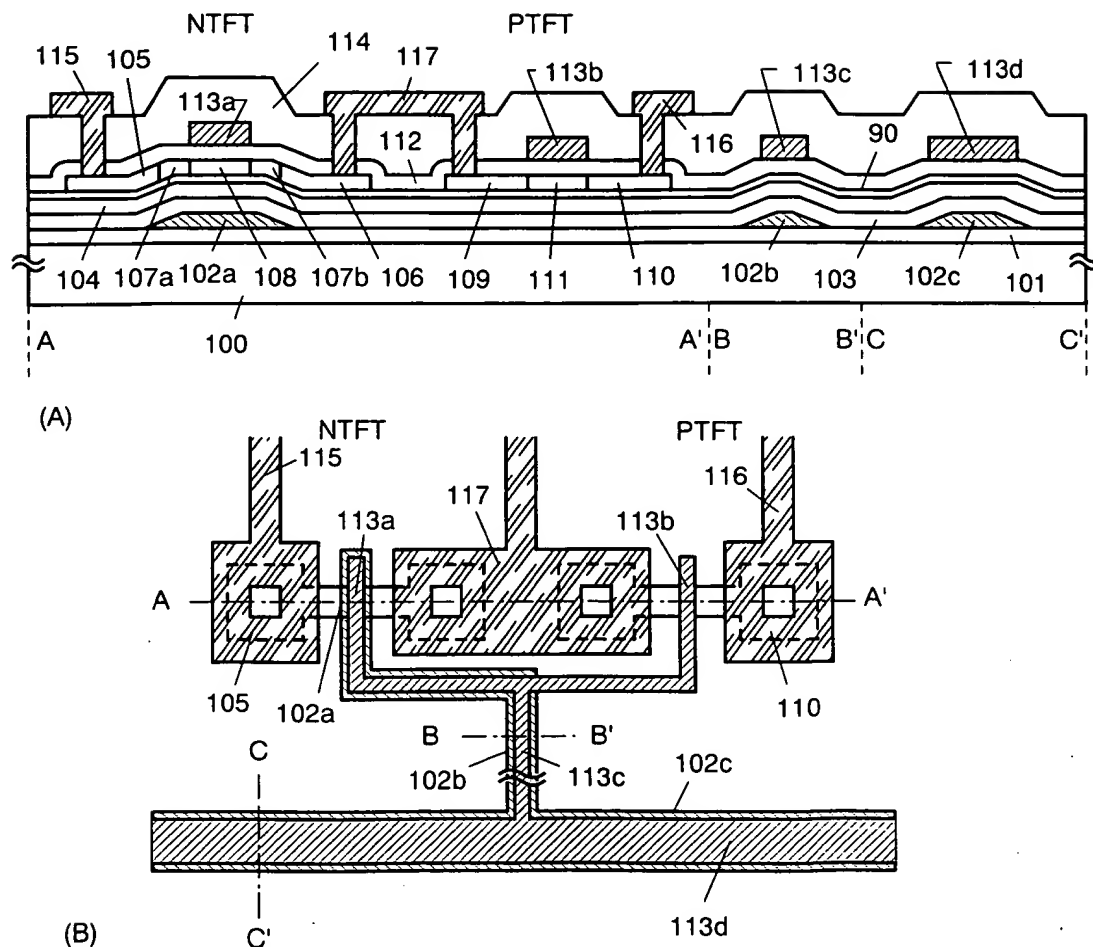




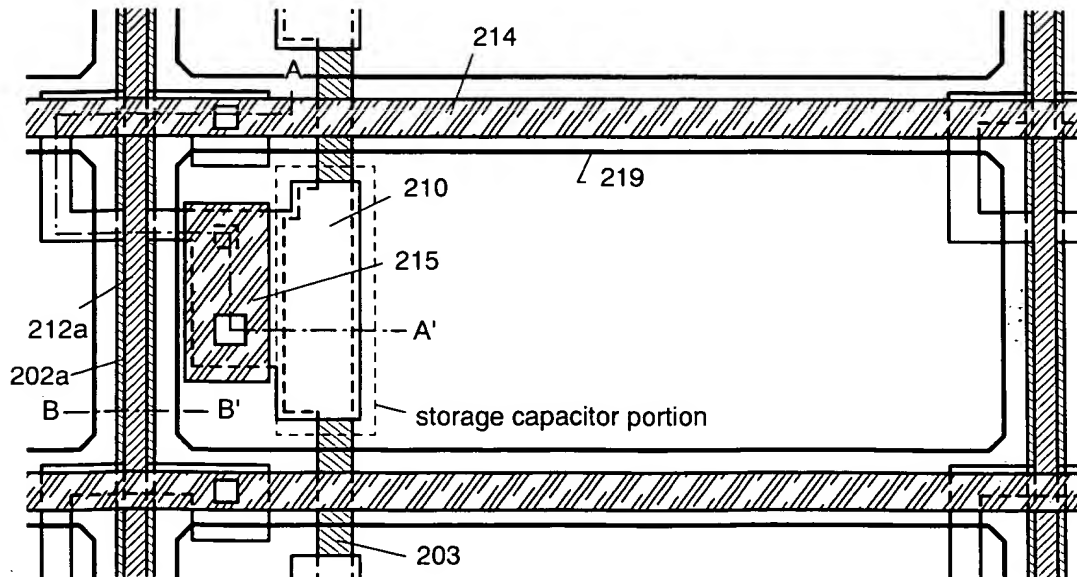
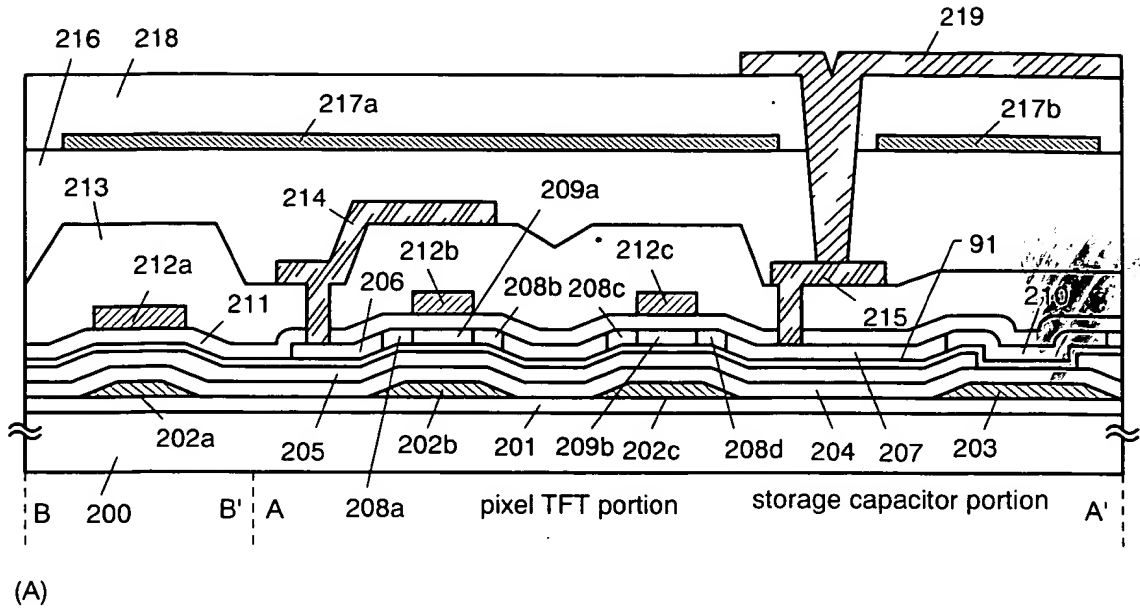
[Name of Document] Drawing

[Fig. 1]



100: substrate 101: base film 102a, 102b, 102c: first wiring lines 103: first insulating layer
 104: second insulating layer 105: source region (NTFT) 106: drain region (NTFT)
 107a, 107b: low concentration impurity region 108: channel formation region
 109: source region (PTFT) 110: drain region (PTFT) 111: channel formation region (PTFT)
 112: second insulating layer 113a, 113b, 113c, 113d: second wiring lines
 114: first interlayer insulating layer 115: source wiring line (NTFT)
 116: source wiring line (PTFT) 117: drain wiring line (in common with NTFT and PTFT)

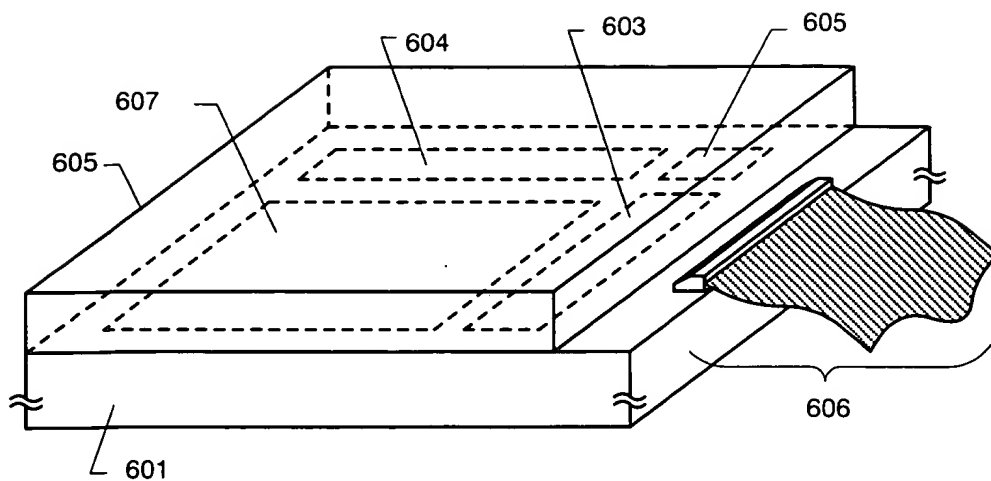
[Fig. 2]



200: substrate 201: base film 202a, 202b, 202c: first wiring lines 203: capacitor wiring line
 204: first insulating layer (TaOx film) 205: second insulating layer 90: silicon oxide film
 206: source region 207: drain region 208a to 208d: low concentration impurity region
 209a, 209b: channel formation region 210: impurity region for a capacitor
 211: third insulating layer 212a, 212b, 212c: second wiring lines
 213: first interlayer insulating layer 214: source wiring line 215: drain wiring line
 216: second interlayer insulating layer 217a, 217b: black mask
 218: third interlayer insulating layer 219: pixel electrode

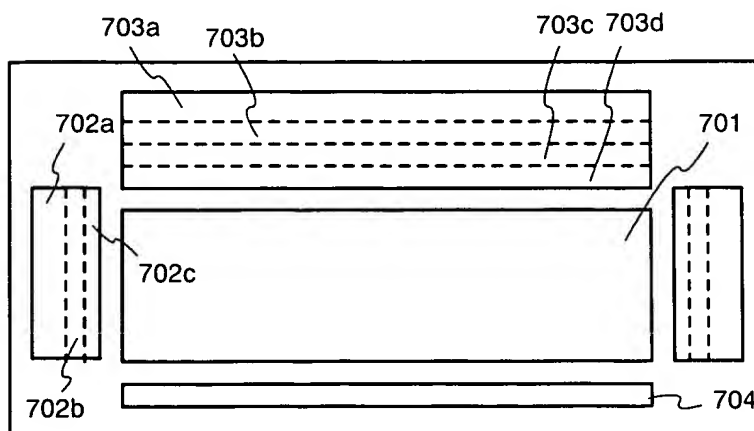


[Fig. 6]



601: substrate with an insulating surface 602: pixel matrix substrate
 603: source driver circuit 604: gate driver circuit
 605: signal processing circuit 606: FPC 607: opposite substrate

[Fig. 7]



701: pixel matrix circuit 702a, 703a: shift register circuit
 702b 703b: level shifter circuit 702c, 703c: buffer circuit
 703d: sampling circuit 704: precharge circuit



[Fig. 18]

